ABSTRACT

ELECTRONIC PACKAGE HAVING A FOLDED FLEXIBLE SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

An electronic package is provided and its method of construction. A microelectronic die is mounted to a flexible substrate. A mold cap is injectionmolded over the die. The mold cap has a curved convex edge surface around which the flexible substrate wraps. Folding of the flexible substrate is controlled by the edge surface to reduce defects, ensure consistent form factor from one package to the next, and allow for the inclusion of a relatively resilient ground plane.

FIG. 3D